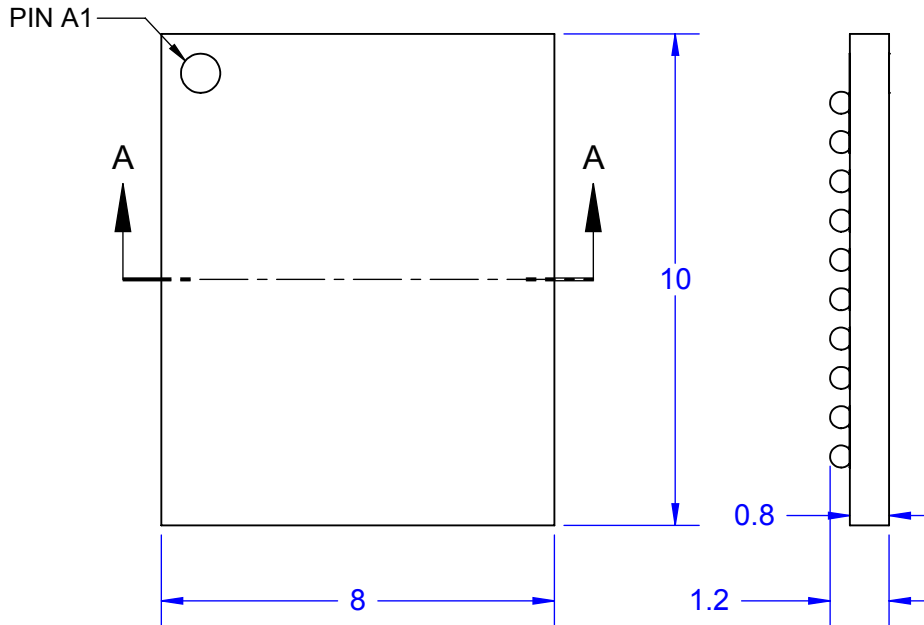
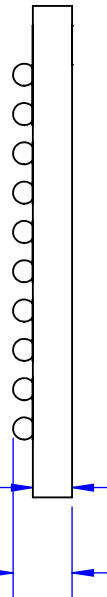


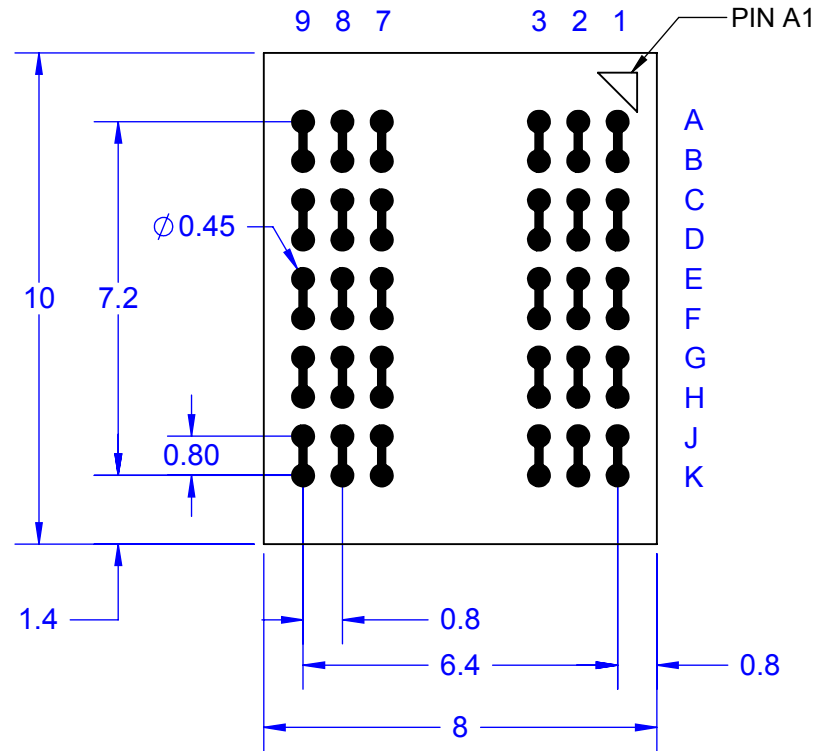
TOP VIEW



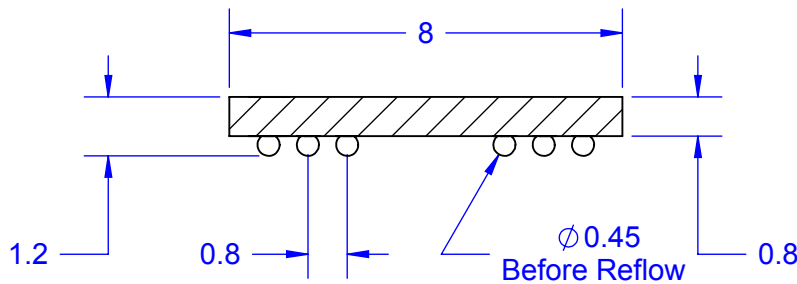
SIDE VIEW



BALL VIEW



EDGE VIEW




SECTION A-A

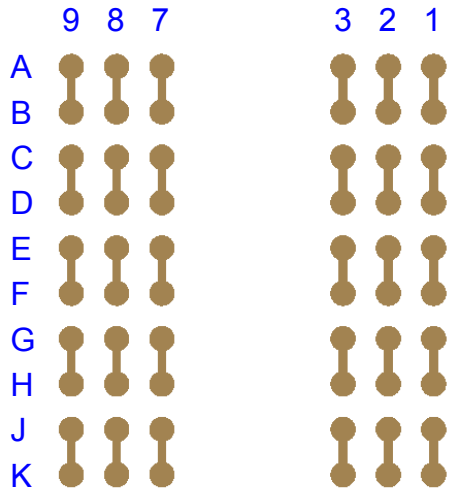
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.45mm (17.7MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.35mm (13.8 MIL).
- 5) PAD Cu DIAMETER: 0.51mm (20 MIL).
- 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
- 7) DUMMY DIE IS NOT INCLUDED.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

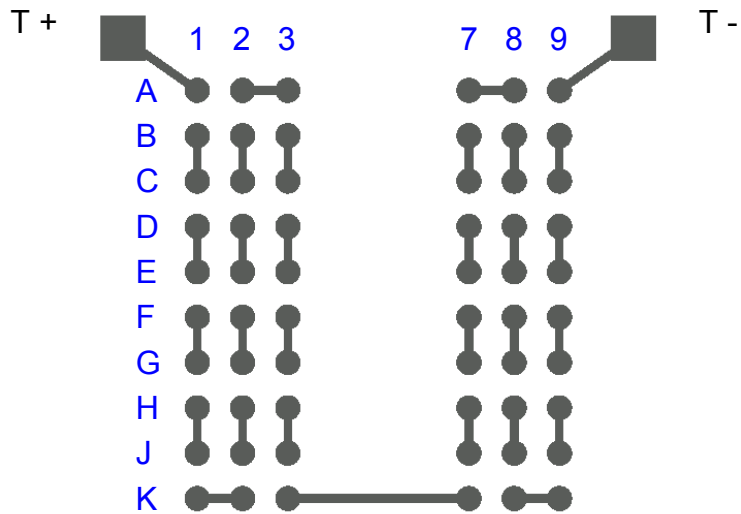
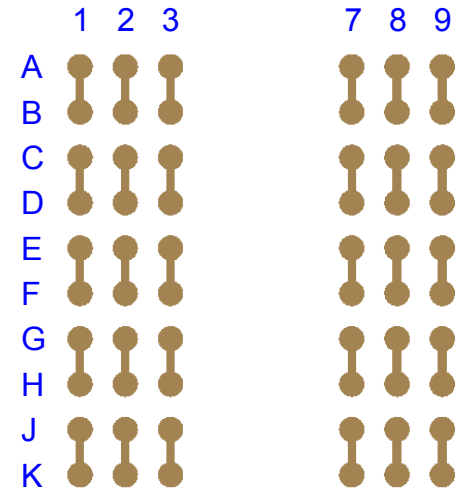
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
LPGA60T.8C-DC610	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LPGA60T.8-DC610	Sn63/Pb37	NO	NO	NO

APPROVALS	DATE				
DRAWN T.Au	11/08/13				
ENG M. Hart	11/08/13	TITLE LPGA60T.8C-DC610 DAISY CHAIN DUMMY			
MFG		SCALE 6.5:1	SIZE A	DRAWING NO. 586101	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 2
CUST					
REVISED					

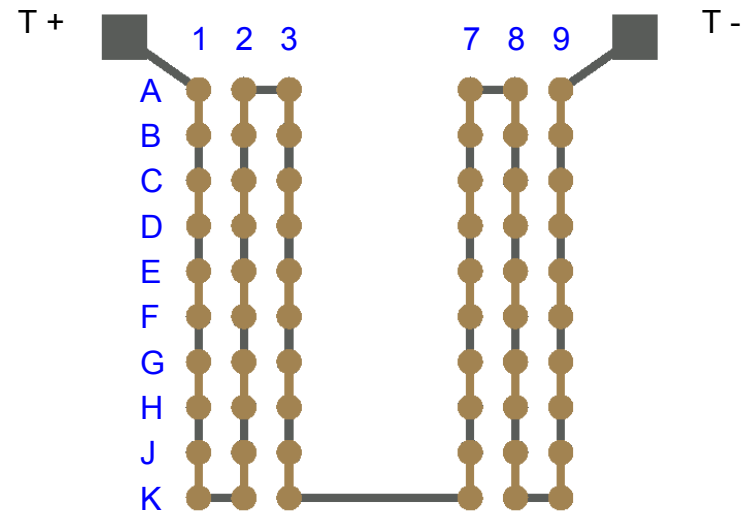
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.51mm (20 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.35mm (13.8 MIL).

TopLine®			
TITLE		LBGA60T.8C-DC610 DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
7.5:1	A	586101	A
DO NOT SCALE DRAWING			SHEET 2 OF 2